



SPECIFICATION FOR APPROVAL

Customer : _____

Part No : MLT-SMD-5050-03060DXX

Developed No : MLT-SP202305003

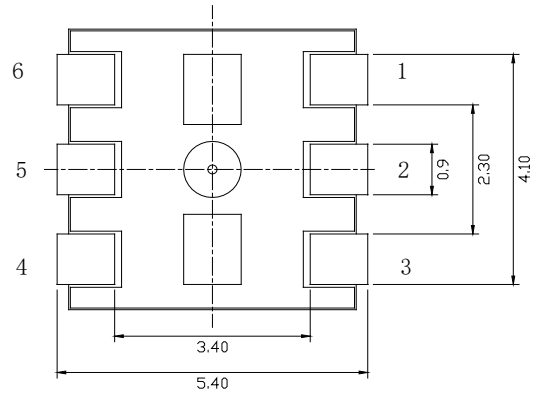
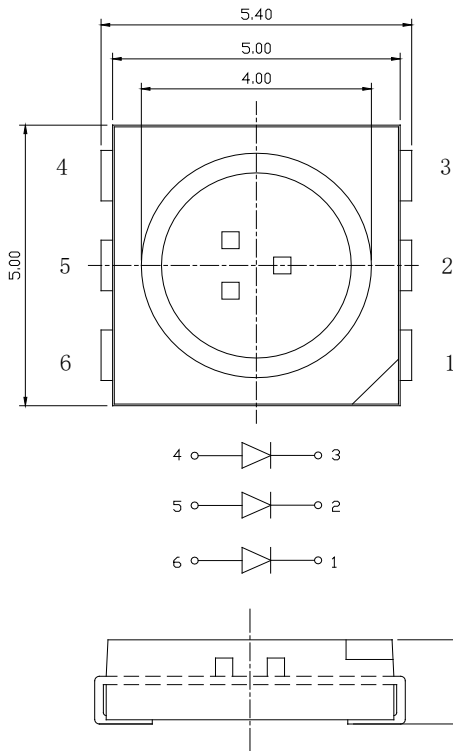
Date : 2023/05/08

CUSTOMER APPROVED BY

APPROVED	Q.C.	R&D



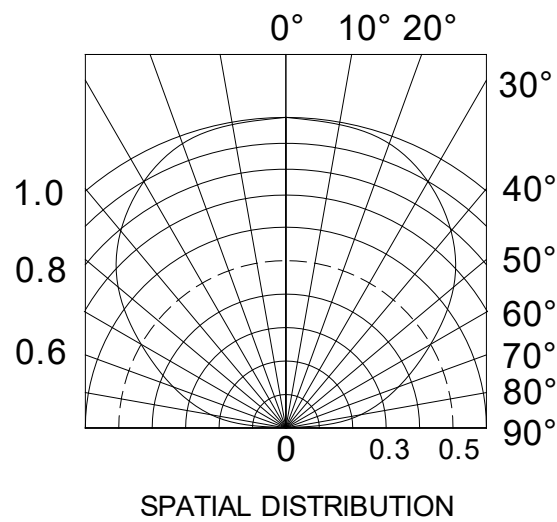
■ Outline Dimension:



Notes:

1. All dimensions are in millimeters.
2. Tolerance is ± 0.2 unless otherwise noted.
3. Specifications are subject to change without notice.

■ View Angle:





Typical Electrical & Optical Characteristics(Ta=25°)

Items	Symbol	Condition	Device	Min	Typ	Max	Unit
Forward Voltage	VF	If =20mA	Chip1	3.0		3.4	V
			Chip2	3.0		3.4	V
			Chip3	3.0		3.4	V
Reverse Current	IR	VR =5V	Chip1	---	---	5	μ A
			Chip2	---	---	5	μ A
			Chip3	---	---	5	μ A
TC (K)		If =20mA	Chip1	6250		6750	K
			Chip2				
			Chip3				
Luminous Flux	Φv	If =20mA	Chip1	6		8	Lm
			Chip2				
			Chip3				
View Angle	2 θ 1/2	If =20mA		---	120	---	Deg

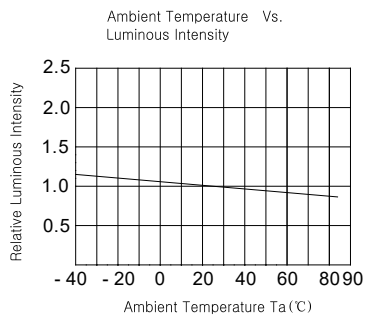
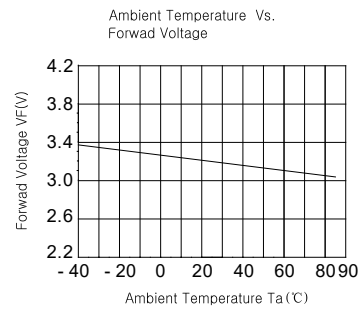
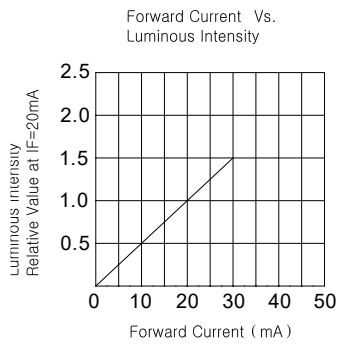
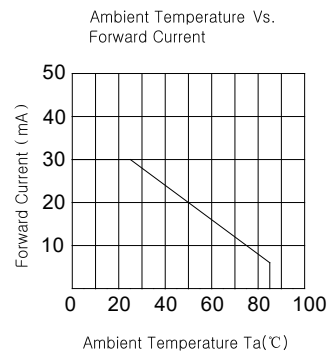
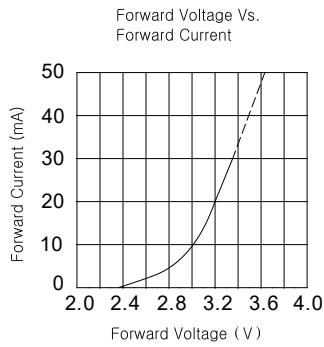
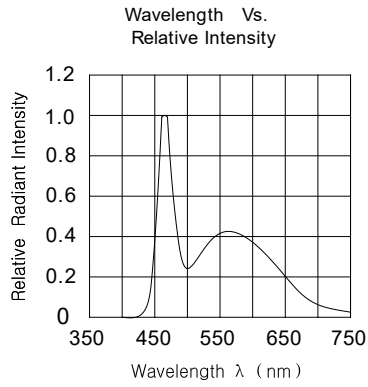
■ Absolute Maximum Ratings (Ta = 25°C)

Items	Symbol	Absolute maximum Rating	Unit
Power Dissipation	PD	120	mW
Forward Current(DC)	IF	30	mA
Peak Forward Current	IFP	150	mA
Reverse Voltage	VR	5	V
Operation Temperature	Topr	- 40~ + 85	°C
Storage Temperature	Tstg	- 40~ + 100	°C

Note :1/10 Duty Cycle, 0.1 ms Pulse Width.



■ Typical Electrical/Optical Characteristics Curves:

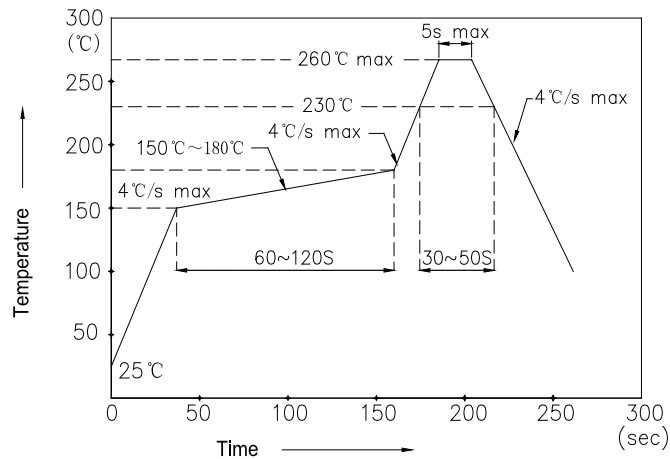




■ Reliability Test :

Classification	Test Item	Test Conditions	Duration	Units Tested	Number of Damaged
Life Test	Operating Life Test	Ta =25°C ± 5°C, RH=55 ± 20%RH, IF=30mA	1000hrs	22	0/22
Environment Test	High Temperature Storage	Ta =100°C ± 10°C	1000hrs	22	0/22
	Low Temperature Storage	Ta = - 40°C ⁺³ / ₋₅ °C	1000hrs	22	0/22
	Temp & Humidity Storage	Ta =85°C ⁺⁵ / ₋₃ °C RH=85 ⁺⁵ / ₋₁₀ %RH	1000hrs	22	0/22
	Thermal Shock Test	Ta= - 40°C ⁺⁵ / ₋₃ °C ~ 100°C ⁺³ / ₋₅ °C T=5min - 5min	100 Cycles	22	0/22
	Temperature Cycling Test	Ta= - 40 ⁺³ / ₋₅ °C ~ 25°C ~ 100 ⁺⁵ / ₋₃ °C ~ 25°C T=30min-5min-30min- 5min	10Cycles	22	0/22

Reflow Soldering Profile For Lead-free SMT Process.



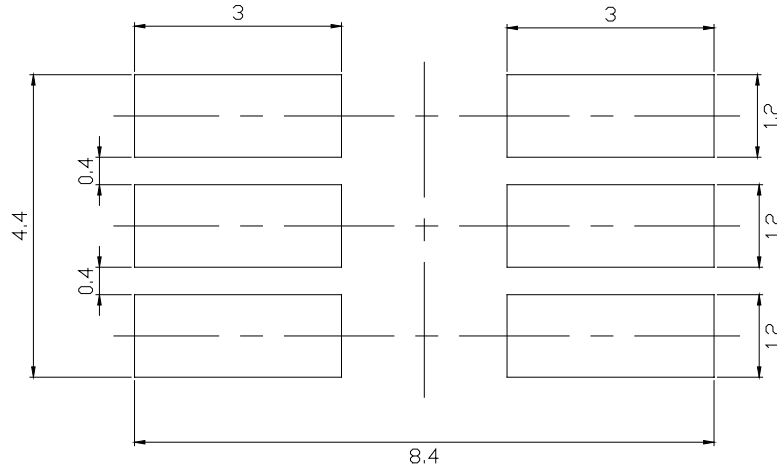
NOTES:

1. We recommend the reflow temperature 245°C (+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.



■ Recommended Soldering Pattern:

(Units:mm)



■ Tape Specifications:

(Units:mm)

